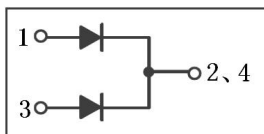


Ultrafast Recovery Diode in a TO-263 Plastic Package.

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

For high frequency, high voltage, high current rectifier diode, freewheeling diode, PFC circuit.



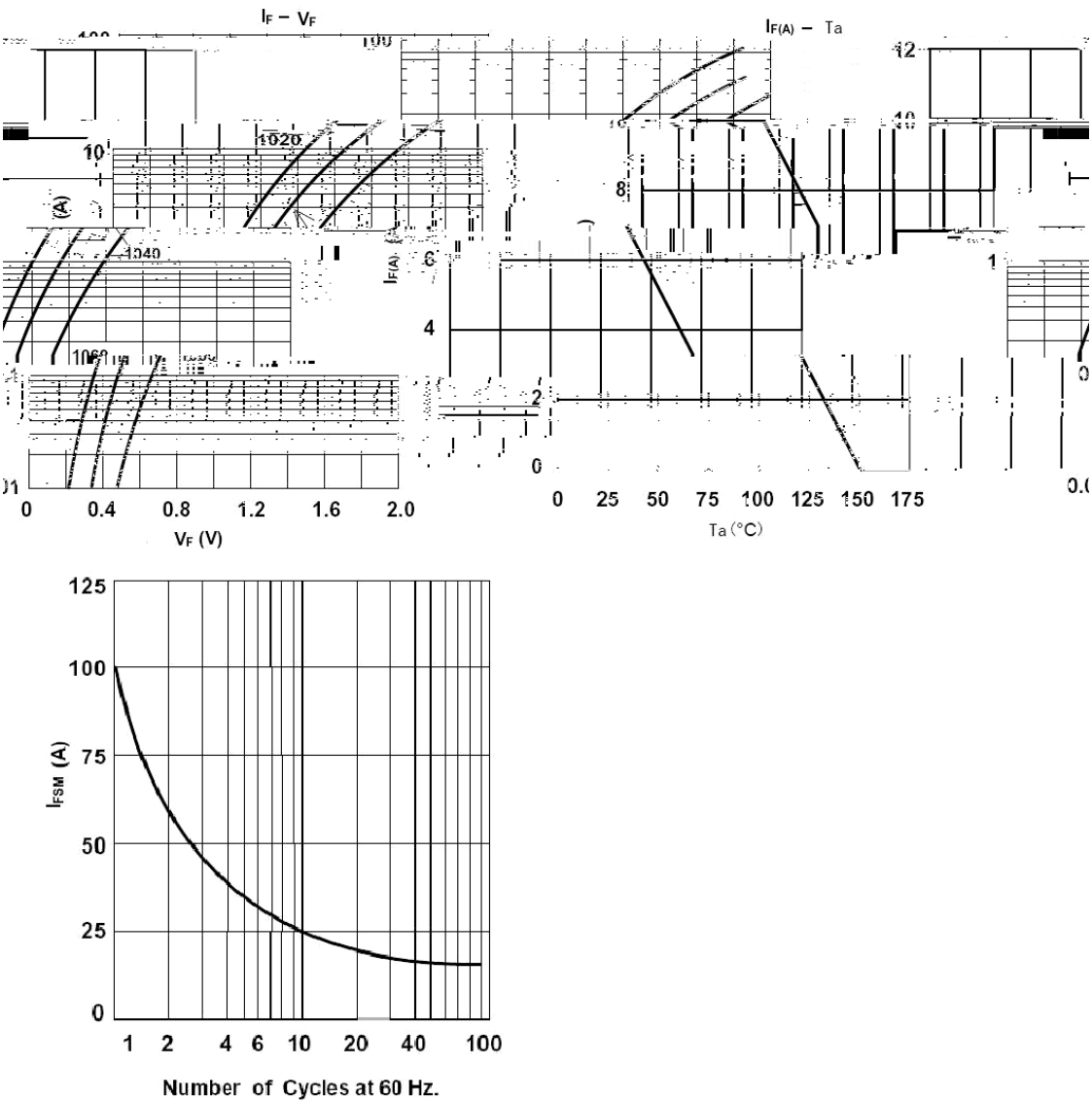
PIN1 Anode

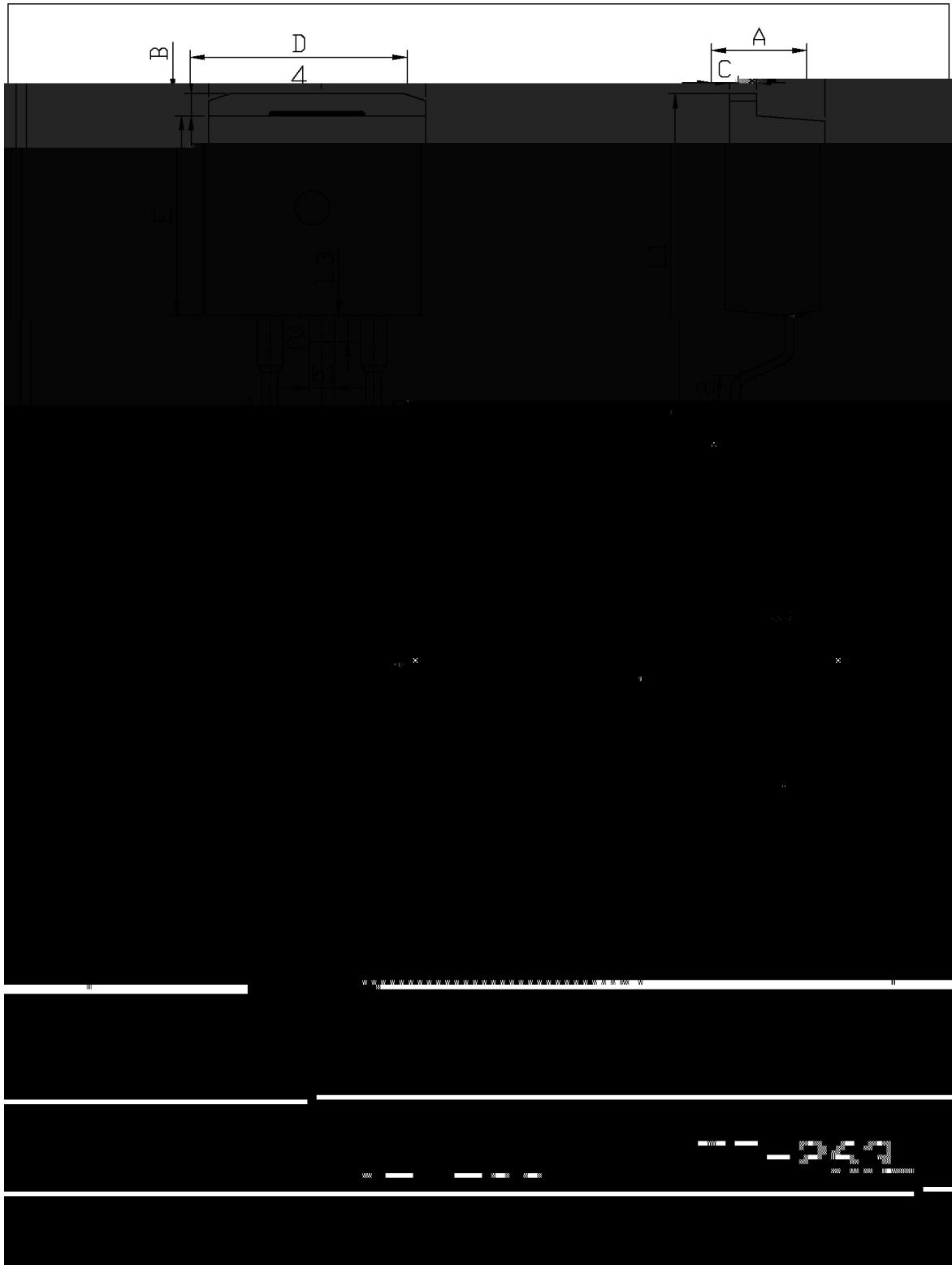
PIN 2 4 Cathode

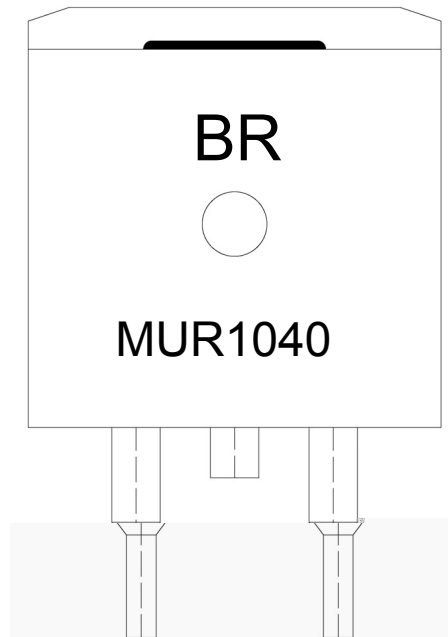
PIN 3 Anode

。 See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	400	V
RMS Voltage	V_{RMS}	280	V
DC Blocking Voltage	V_{DC}	400	V
Peak Repetitive Forward Current	I_F	10	A
Non Repetitive Peak Surge Current	I_{FSM}	100	A
Maximum Thermal Resistance Junction to Case	$R_{\theta Jc}$	2.8	/W
Storage Temperature Range	T_{stg}	-55~150	







Note:

BR:

Company Code

MUR1040:

Product Type

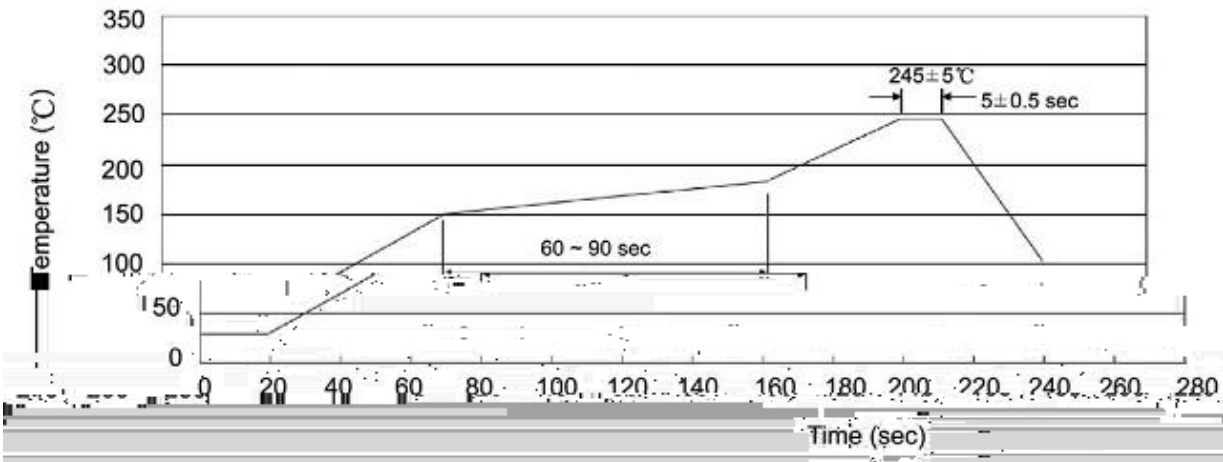
CT:

Internal Structure

****:

Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

255 5

5 0.5sec;

2.Peak Temp.:255 5 , Duration:5 0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

260 5

10 1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
						"		

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱